

**REMARKS**

Claims 1-10 and 12 are canceled. Claim 11 is amended to incorporate the subject matter of claim 12. No new matter is presented. Accordingly, upon entry of the Amendment, claims 11 and 13-20 will be all of the claims pending in the application.

**I. Information Disclosure Statement**

The Examiner indicates that the Information Disclosure Statement filed on September 26, 2003, was received but that the PTO/SB/08 Form was lost and the Examiner requests Applicants to submit a copy of the PTO/SB/08 form.

A copy of the lost PTO/SB/08 Form is attached in response to the Examiner's request. Applicants respectfully request the Examiner to return an initialed copy of the attached form.

**II. Response to Claim Rejections**

Claims 11-14 and 17-20 are rejected under 35 U.S.C. § 102(e) as allegedly being anticipated by or, in the alternative, under 35 U.S.C. § 103(a) as allegedly being obvious over Murakami et al.

Claims 11-20 are rejected under 35 U.S.C. § 103(a) as allegedly being unpatentable over the combination of Murakami et al., Japanese Publication 2001-049129 (JP '129), Ueno et al., Tamura '722 and Tamura et al '966.

Claims 11-14 are rejected under 35 U.S.C. § 102(e) as allegedly being anticipated by Levy.

Applicants respectfully traverse the rejections and submit that the cited references do not disclose, teach or suggest the presently claimed invention.

Claim 11 is amended herein to recite a stereolithographic method, wherein the stereolithographic resin composition comprises a photo-curable component, a sol-gel resin material having a function of causing a reversible, quick sol-gel phase transition based on temperature change, and a thermally conductive filler.

None of the cited references discloses, teaches or suggests a thermally conductive filler as recited in the present claims. The present application discloses a filler effective for heat diffusion on page 11, lines 6-20. A sol-gel resin which is heated is supplied as a thin layer, and the phase of the layer changes into a gel state at once. Therefore, since the filler contained therein does not settle, the resin can include a highly thermally conductive filler containing a metal with high specific gravity.

In a stereolithographic method, the generation of thermal distortion caused by polymerization heat at the time of resin curing is a significant problem that reduces formation precision. The present invention provides a highly thermally conductive resin for stereolithography and can attain highly precise formation, which has not been attained by conventional stereolithographic methods. Thus, the present invention is neither anticipated nor rendered obvious over the art of record.

Accordingly, Applicants respectfully request withdrawal of the rejections.

### **III. Conclusion**

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the

AMENDMENT UNDER 37 C.F.R. § 1.111  
U.S. APPLN. NO. 10/670,608

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Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.


Respectfully submitted,

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